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April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

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#### **DATA SHEET**



## MOS FIELD EFFECT TRANSISTOR NP160N04TUG

### SWITCHING N-CHANNEL POWER MOS FET

#### **DESCRIPTION**

The NP160N04TUG is N-channel MOS Field Effect Transistor designed for high current switching applications.

#### ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE		
NP160N04TUG-E1-AY Note					
NP160N04TUG-E2-AY Note	Pure Sn (Tin)	Tape 800 p/reel	TO-263-7pin (MP-25ZT) typ. 1.5 g		

Note Pb-free (This product does not contain Pb in the external electrode).

#### **FEATURES**

• Super low on-state resistance

 $R_{DS(on)}$  = 1.6 m $\Omega$  TYP. / 2.0 m $\Omega$  MAX. (Vgs = 10 V, ID = 80 A)

High Current Rating

 $I_{D(DC)} = \pm 160 A$ 

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (VGS = 0 V)	Voss	40	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	I <sub>D(DC)</sub>	±160	Α
Drain Current (pulse) Note1	I <sub>D(pulse)</sub>	±640	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	220	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	1.8	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Single Avalanche Energy Note2	Eas	372	mJ
Repetitive Avalanche Current Note3	IAR	61	Α
Repetitive Avalanche Energy Note3	Ear	372	mJ

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

2. Starting T<sub>ch</sub> = 25°C, V<sub>DD</sub> = 20 V, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = 20  $\rightarrow$  0 V, L = 100  $\mu$ H

3. Rg = 25  $\Omega$ , Tch(peak)  $\leq 150^{\circ}$ C

#### THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	0.68	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W

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(TO-263-7pin)



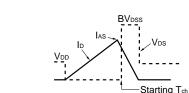
#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V			1	μΑ
Gate Leakage Current	Igss	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100	nA
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	3.0	4.0	V
Forward Transfer Admittance Note	yfs	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 40 A	28	76		S
Drain to Source On-state Resistance Note	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 80 A		1.6	2.0	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 25 V,		10500	15750	pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V,		980	1470	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		630	1140	pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 80 A,		47	110	ns
Rise Time	tr	V <sub>GS</sub> = 10 V,		67	170	ns
Turn-off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> = 0 Ω		94	190	ns
Fall Time	tf			19	50	ns
Total Gate Charge Note	Q <sub>G</sub>	V <sub>DD</sub> = 32 V,		178	270	nC
Gate to Source Charge	QGS	V <sub>GS</sub> = 10 V,		44		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 160 A		61		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	IF = 160 A, VGS = 0 V		0.92	1.5	V
Reverse Recovery Time	trr	I <sub>F</sub> = 160 A, V <sub>GS</sub> = 0 V,		50		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/µs		75		nC

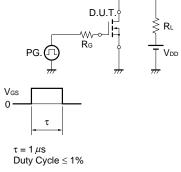
Note Pulsed test

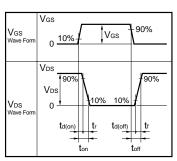
#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $\begin{array}{c} \text{D.U.T.} \\ \text{Rg} = 25 \ \Omega \\ \text{Vgs} = 20 \rightarrow 0 \ \text{V} \end{array} \begin{array}{c} \text{PG.} \\ \text{M} \end{array} \begin{array}{c} \text{S} \\ \text{S} \\ \text{S} \end{array} \begin{array}{c} \text{D.U.T.} \\ \text{In } \\ \text{M} \end{array} \begin{array}{c} \text{VDD} \\ \text{M} \end{array}$



#### **TEST CIRCUIT 2 SWITCHING TIME**





#### TEST CIRCUIT 3 GATE CHARGE

$$\begin{array}{c|c}
D.U.T. & \\
I_G = 2 \text{ mA} & \\
\hline
PG. & \\
\end{array}$$

$$\begin{array}{c|c}
PG. & \\
\end{array}$$

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\end{array}$$

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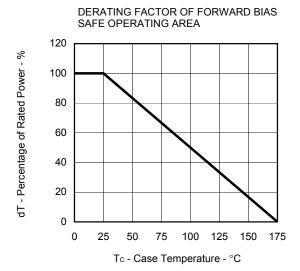
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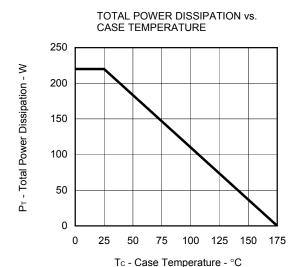
$$\begin{array}{c|c}$$

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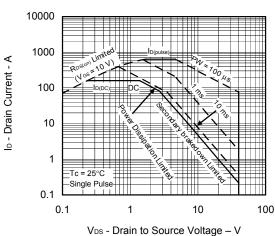
$$\begin{array}{c|c}$$

#### TYPICAL CHARACTERISTICS (TA = 25°C)

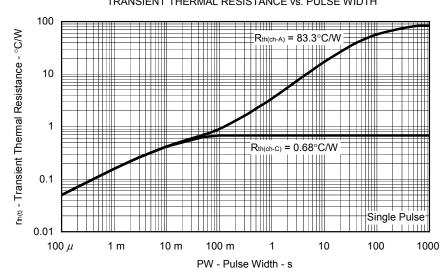




#### FORWARD BIAS SAFE OPERATING AREA



#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

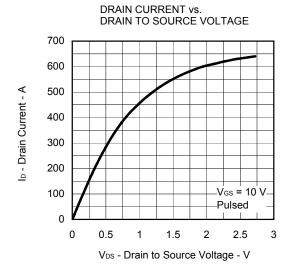


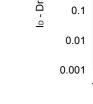
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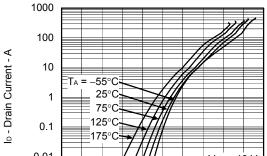
Pulsed

5

6







2

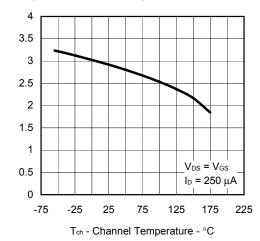
FORWARD TRANSFER CHARACTERISTICS

V<sub>GS</sub> - Gate to Source Voltage - V

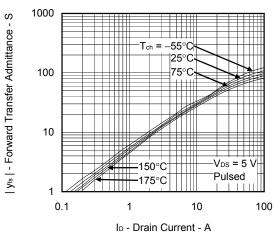
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3

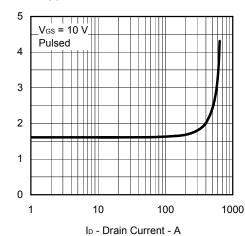
GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



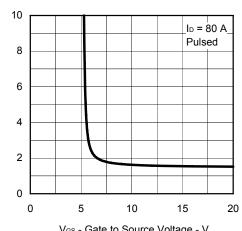
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



V<sub>GS</sub> - Gate to Source Voltage - V

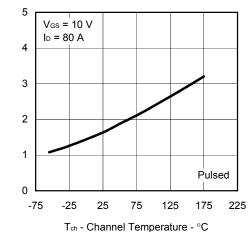
RDS(m) - Drain to Source On-state Resistance - m\Omega

Ves(th) - Gate to Source Threshold Voltage - V

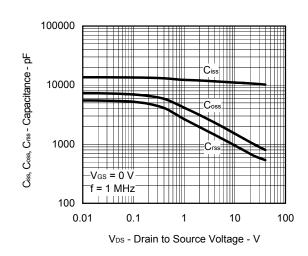
R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

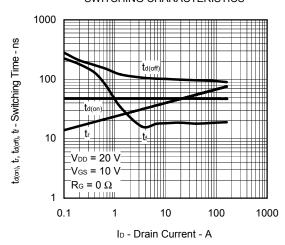




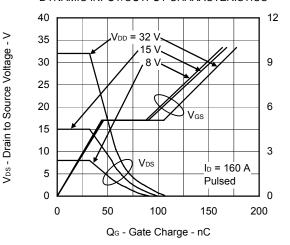
#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



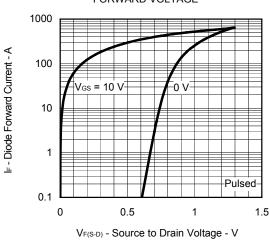
#### SWITCHING CHARACTERISTICS



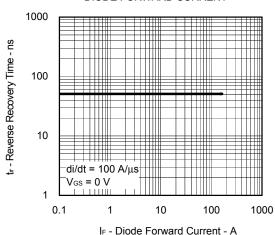
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

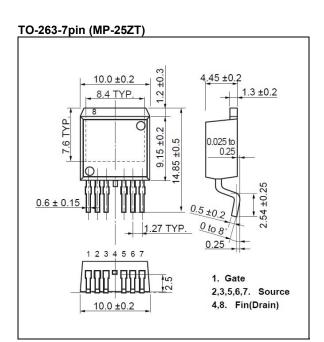


REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

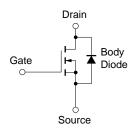


Ves - Gate to Source Voltage - V

#### PACKAGE DRAWING (Unit: mm)



#### **EQUIVALENT CIRCUIT**

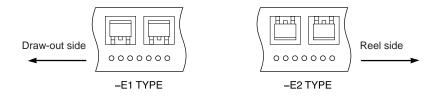


**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

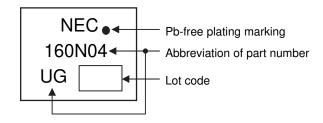
6

#### TAPE INFORMATION

There are two types (-E1, -E2) of taping depending on the direction of the device.



#### MARKING INFORMATION



#### RECOMMENDED SOLDERING CONDITIONS

The NP160N04TUG should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, please contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Soldering Method	Soldering Conditions	Recommended Condition Symbol	
Infrared reflow	Maximum temperature (Package's surface temperature): 260°C or below		
	Time at maximum temperature: 10 seconds or less  Time of temperature higher than 220°C: 60 seconds or less	IR60-00-3	
	Preheating time at 160 to 180°C: 60 to 120 seconds		
	Maximum number of reflow processes: 3 times		
	Maximum chlorine content of rosin flux (percentage mass): 0.2% or less		
Partial heating	Maximum temperature (Pin temperature): 350°C or below		
	Time (per side of the device): 3 seconds or less	P350	
	Maximum chlorine content of rosin flux: 0.2% (wt.) or less		

Caution Do not use different soldering methods together (except for partial heating).

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